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VDE/VDI-Society Microelectronics, Microsystems- and Precision Engineering (GMM)

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In cooperation with:

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Venue: Hilton Hotel in Dresden



Dresden at the river Elbe

The EMLC 2012 International Program Committee

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UBC Microelectronics,
Ammerbuch, Germany

Co-Conference Chair Naoya Hayashi, DNP, Saitama, Japan
Chris Gale, Applied Materials, Dresden,
Germany

Program Chairs Rolf Seltmann, Globalfoundries,
Dresden, Germany
Jo Finders, ASML, Veldhoven,
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Stefan Wurm, SEMATECH, Albany, NY, USA
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Please find the members of the **International Steering Committee** of the EMLC on the website: www.emlc2012.com

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GMM

VDE/VDI-GESELLSCHAFT
MIKROELEKTRONIK, MIKROSYSTEM-
UND FEINWERKTECHNIK



Call for Papers

The 28th European Mask and Lithography Conference EMLC 2012

January 17 – 18, 2012

Hilton Hotel

Dresden, Germany

www.EMLC2012.com



The VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, SEMI-Europe, and SPIE, are pleased to announce the

**28th European Mask and Lithography
Conference, EMLC 2012
at the Hilton Hotel in Dresden, Germany
January 17 - January 18, 2012**

The focus of this two-day conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where mask makers, mask users, and their tool suppliers become acquainted with new developments and results.

Conference Schedule

The conference will start on Tuesday, January 17, 2012, at 09:00 AM with a Keynote Session. The conference will close on Wednesday, January 18, 2012, late afternoon. The Poster Session will be held on Tuesday evening followed by the Conference Banquet Dinner.

Technical Exhibition

On Tuesday and Wednesday there will be a technical exhibition with booth space for about 30 exhibitors. Presentation tables and pin boards will be available. To be part of this Technical Exhibition, please return the **enclosed registration form** to the conference chairperson as soon as possible, since exhibition space is limited.

Conference Chairperson and Exhibition Organization

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Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of two pages including (figures, diagrams, formatted text) as Word and PDF.

Commercial papers, papers with no new research/development content, and papers where significant information is missing will not be accepted.

All accepted abstracts will be printed, bound and handed out to the participants of the conference.

In order to submit your abstract, please open the web site

www.EMLC2012.com

There you will find a link to myspie.org

Deadline for Abstracts: September 30th 2011

By submitting an abstract you agree to

- Present your work in person at the conference
- Submit a manuscript in time

Authors will be notified of the acceptance of their submissions by **October 21st 2011**; further manuscript format and layout instructions will be provided at that time.

Manuscripts:

Please submit the original of the manuscript a.s.a.p.

As to further information concerning the submission procedure, please have a look at our homepage, **www.emlc2012.com**

Deadline for Manuscripts: December 2nd 2011

All manuscripts will be subject to a critical peer review before they are accepted for publication in the SPIE Digital Library.

Please note: Late submissions may not be published.

Information on the format of the manuscripts and further details is also provided at the conference web site:

www.emlc2012.com

The conference manuscripts will be published by SPIE

Conference Topics

Presentations are solicited for the following and related topics:

Mask Manufacturing

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET & OPC; PSM
- Masks for NGL: E-Beam, EUV, NIL, etc.

Mask Business

- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithography and Mask Application

- Double Patterning
- RET, OPC, PSM, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids
- Lithography Process Control
- Lithography Simulation

Emerging Mask and Lithography Technologies

- EUV Materials, Tools & Processes
- EUV Mask Infrastructure
- NIL
- Direct Write / Maskless Technologies

Mask and Lithography Equipment

- Mask Manufacturing

Semiconductors applied in Automotive

NEW !!

Semiconductors in MEMS Applications

NEW !!

Patterned Media

NEW !!